

IN THE CLAIMS:

Please cancel/amend/retain the claims as follows:

1. (Currently Amended) A stack chip module including:

a substrate having a predetermined-size groove ~~on one side~~ and a circuit pattern on each side, with one end of each circuit pattern being adjacent to a respective the groove, said grooves being arranged on both sides of said substrate in a jig-jag form;

a first semiconductor chip adhered in the each groove of the substrate by adhesive, each of said first semiconductor chips and having a plurality of center pads and a plurality of edge pads, electrically connected to each other, on an upper part thereof;

a plurality of gold wires for electrically connecting the a respective circuit pattern of the substrate and the edge pads of the a respective first semiconductor chip, respectively;

for each of said first semiconductor chips, a second semiconductor chip having a plurality of center pads corresponding to said plurality of center pads on said upper part of the respective first semiconductor chip and the a formative side being opposite to that of the respective first semiconductor chip;

a plurality of bumps interposed between the center pads of the first semiconductor ~~chip chips~~ and the center pads of the corresponding second semiconductor ~~chip chips~~ for joining and electrically connecting said respective center pads; and

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a molding material molding a side of the second semiconductor chips chip including the gold wires, the edge pads of the first semiconductor chip chips and the circuit pattern patterns of the substrate.

Claims 2-3 (Canceled).

4. (Original) The stack chip module according to claim 1, wherein the bumps have a height of 40 to 100 μ m.

Claims 5-10 (Canceled).